



## Customer Information Notification

201403005I

**Issue Date:** 17-Nov-2014  
**Effective Date:** 15-Feb-2015

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



# QUALITY

### Change Category

- |  |   |   |  |
|--|---|---|--|
| <input type="checkbox"/> Wafer Fab process   | <input type="checkbox"/> Assembly Process   | <input type="checkbox"/> Product Marking                | <input type="checkbox"/> Design                              |
| <input type="checkbox"/> Wafer Fab materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input checked="" type="checkbox"/> Mechanical Specification |
| <input type="checkbox"/> Wafer Fab location  | <input type="checkbox"/> Assembly Location  | <input type="checkbox"/> Test Location                  | <input type="checkbox"/> Packing/Shipping/Labeling           |

## Datasheet update - Thinner lead frame material

### Information Notification

With PCN 200408018F from y 2004 a thinner lead frame material for the SOT89 package has been implemented.

During this implementation the relevant datasheet for the types BSS87 and BSS192 has not been updated with the new lead frame specification.

The minimum limit for the lead frame thickness has been changed from 0.37mm to 0.23mm.

With this CIN we announce an updated datasheet with the corrected lead frame specification. In addition the datasheet contains enhanced product information and graphs.

A new datasheet will be available on our NXP website soon.

#### **Why do we issue this Information Notification**

datasheet update

#### **Identification of Affected Products**

no change to current production

thinner lead frame has already been implemented in y 2004

### Impact

no impact to the product's functionality anticipated.

#### **Data Sheet Revision**

A new datasheet will be issued

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** GA Customer Support

**e-mail address** DiscrQA.Helpdesk.GA-Products@nxp.com

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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